

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L2	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L3	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L4	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L5	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L6	1146	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L7	125	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L8	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L9	3	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L10	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L11	2	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44

L12	202	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L13	144	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L14	69	interconnect near3 copper with transistor	USPAT	OR	ON	2005/12/15 15:44
L15	1	"4939568".pn.	USPAT	OR	ON	2005/12/15 15:44
L16	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L17	46	("20020050635" "20020077467" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L18	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L19	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L20	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L21	62	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L22	1146	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L23	202	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44

L24	62	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L25	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L26	1	"4939568".pn.	USPAT	OR	ON	2005/12/15 15:44
L27	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L28	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L29	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L30	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L31	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L32	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L33	3	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L34	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L35	2	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L36	69	interconnect near3 copper with transistor	USPAT	OR	ON	2005/12/15 15:44

L37	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L38	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L39	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L40	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
L41	125	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L42	144	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
L43	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44